



Ventiva closes \$10M Series C Investment Round

January 2, 2024 – [Ventiva®](#), a leading company in active cooling solutions for electronic devices, is excited to announce the successful completion of its \$10 million Series C funding round. The investment round funding was obtained from a balanced mix of new money from multiple investment funds along with strong participation from existing investors.

The investment brings the total amount raised by Ventiva since inception to more than \$40 million and will be used to further accelerate the company’s expansion, ongoing development of its state-of-the-art technology, and delivery of first-class service to customers.

Commenting on the investment, Carl Schlachte, Chairman, President and CEO of Ventiva said, “Despite a difficult fundraising environment for tech companies, this funding round demonstrates clear understanding among investors that the consumer electronics markets are eager for a silent, vibration-free, solid-state active thermal solution and Ventiva has that solution. Ventiva has an immense untapped market opportunity ahead.”

Ventiva is gearing up to launch its latest generation groundbreaking Ionic Cooling Engine (ICE®), initially tailored for the laptop market. Following this, the company will expand its ICE® technology to a diverse range of applications, including AR/VR, television, portable gaming modules, and various cutting-edge electronics.

Headquartered in Silicon Valley, Ventiva sets the standard in advanced thermal research and development for electronic devices. Its flagship ICE® technology, based on principles of electrohydrodynamic flow that intersect physics, engineering and fluid dynamics, is enabling high-performance devices to be more lightweight, silent and vibration-free.

About Ventiva

[Ventiva®](#), a leading company in active cooling solutions for electronic devices, is enabling smaller, faster, and more functional high-performance devices that are lightweight, silent and vibration-free. The company’s patented ICE® technology intersects physics, engineering and fluid dynamics to become the first new commercial cooling architecture for electronics.

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